

Part Number: **BAS16TW-p-F**
Weight (mg): 6.37
(HF Date Code 0740+)

p=package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	2.04	0.13	1000000	20383
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	30.84	1.96	576500	177806
		Ni	7440-02-0	41.00%			410000	126453
		Mn	7439-96-5	0.60%			6000	1851
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	308
		Co	7440-48-4	0.50%			5000	1542
		Si	7440-21-3	0.15%			1500	463
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.95	0.06	1000000	9516
Bond Wire	Copper Wire	Cu	7440-50-8	100.00%	0.21	0.01	1000000	2136
Encapsulation	CEL-1702HF-9	SiO2	60676-86-0	87.30%	59.73	3.80	873000	521426
		Epoxy Resin	29690-82-2	5.00%			50000	29864
		Phenol Resin	26834-02-6	5.00%			50000	29864
		Aromatic poly-phosphate	----	2.50%			25000	14932
		C	1333-86-4	0.20%			2000	1195
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	6.23	0.40	1000000	62262
Total					100.00	6.37		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
4,4'- Diaminodiphenylmethane	Bis (2-ethyl(hexyl)phthalate) (DEHP)
Dibutyl phthalate	Hexabromocyclododecane (HBCDD)
Cyclododecane	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cobalt dichloride	Bis(tributyltin)oxide
Diarsenic pentoxide	Lead hydrogen arsenate
Diarsenic trioxide	Triethyl arsenate
Sodium dichromate, dihydrate	Benzyl butyl phthalate